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Sheet 1 of 1

Complete if Known

Application Number	10/767,483
Filing Date	January 28, 2004
First Named Inventor	Vaidyanathan
Art Unit	3753
Examiner Name	Unassigned
Attorney Docket Number	003248.00093

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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FOREIGN PATENT DOCUMENTS

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S.A		C. Bower, A. Ortega, P. Skandakumaran, R. Vaidyanathan and T. Phillips, "Heat Transfer in Water-Cooled Silicon Carbide Mill-channel Heat Sinks for High Power Electronic Applications", Proceedings of IMECE 2003, Washington, DC	
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Examiner Signature		Date Considered	5/10/2006
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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